

# SOT566-2

plastic, heatsink small outline package; 24 leads; low stand-off height

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HSOP24
<b>Package type industry code</b>	HSOP24
<b>Package style descriptive code</b>	HSOP (heatsink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-7-2003

Table 1. Package summary

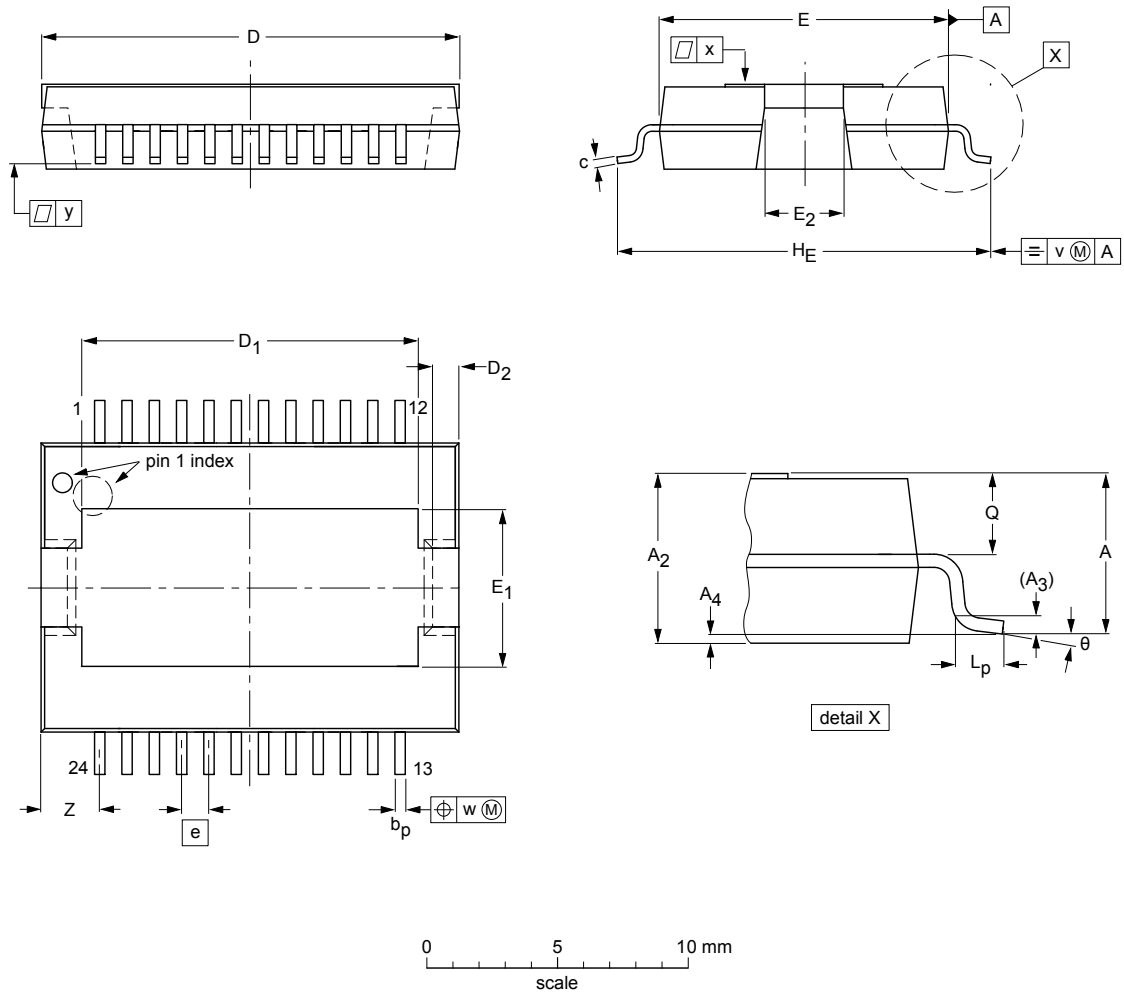
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.8	-	15.9	16	mm
E	package width	10.9	-	11	11.1	mm
A	seated height	[tbd]	-	3.5	3.5	mm
A <sub>2</sub>	package height	3.2	-	3.35	3.5	mm
n <sub>2</sub>	actual quantity of termination	-	-	24	-	



2. Package outline

HSOP24: plastic, heatsink small outline package; 24 leads; low stand-off height

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>2</sub>	A <sub>3</sub>	A <sub>4</sub> (1)	b <sub>p</sub>	c	D(2)	D <sub>1</sub>	D <sub>2</sub>	E(2)	E <sub>1</sub>	E <sub>2</sub>	e	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	x	y	Z	θ
mm	3.5	3.5 3.2	0.35	+0.12 -0.02	0.53 0.40	0.32 0.23	16.0 15.8	13.0 12.6	1.1 0.9	11.1 10.9	6.2 5.8	2.9 2.5	1	14.5 13.9	1.1 0.8	1.7 1.5	0.25	0.25	0.03	0.07	2.7 2.2	8° 0°

Notes

- Limits per individual lead.
- Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT566-2						-03-02-18 03-07-23

Fig. 1. Package outline HSOP24 (SOT566-2)

### 3. Legal information

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## 4. Contents

---

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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